TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (U-MOSVI-H)

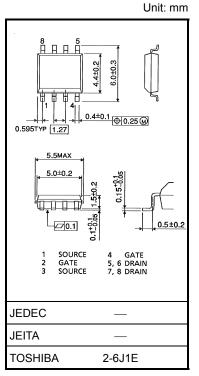
# **TPC8218-H**

# DC-DC Converter Applications CCFL Inverters

- · Small footprint due to a small and thin package
- High-speed switching
- Small gate charge: Q<sub>SW</sub> = 2.6 nC (typ.)
- Low drain-source ON-resistance:  $R_{DS}$  (ON) = 38 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fS}| = 12 S$  (typ.)
- Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 60 \text{ V)}$
- Enhancement mode:  $V_{th} = 1.3$  to 2.3 V ( $V_{DS} = 10$  V,  $I_{D} = 0.1$  mA)

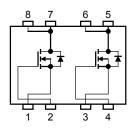
#### Absolute Maximum Ratings ( $Ta = 25^{\circ}C$ )

Cha	racteristic	Symbol	Rating	Unit	
Drain-source vo	Itage	$V_{DSS}$	60	V	
Drain-gate volta	ge (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	60	V	
Gate-source vol	tage	V <sub>GSS</sub>	±20	V	
Drain current	D C (Note 1)	I <sub>D</sub>	3.8	Α	
Diain current	Pulse (Note 1)	$I_{DP}$	15.2	A	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.5	W	
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D</sub> (2)	1.1		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.75		
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.45	W	
Single-pulse ava	lanche energy (Note 4)	EAS	10	mJ	
Avalanche curre	nt	I <sub>AR</sub>	3.8	Α	
Repetitive avalar (Note	nche energy e 2a, Note 3b, Note 5)	EAR	0.03	mJ	
Channel tempera	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ture range	T <sub>stg</sub>	-55 to 150	°C	



Weight: 0.085 g (typ.)

#### **Circuit Configuration**



Note: For Notes 1 to 5, refer to the next page.

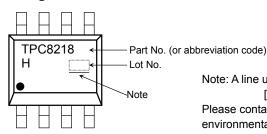
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating" Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

#### **Thermal Characteristics**

Characteristic	Symbol	Max	Unit		
The small resistance about 1 to embient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3	_	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	114	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	167	C/VV	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	278		

#### Marking

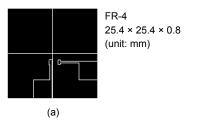


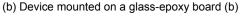
Note: A line under a Lot No. identifies the indication of product Labels.

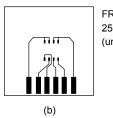
[[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]
Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)







FR-4 25.4 × 25.4 × 0.8 (unit: mm)

#### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (Initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 3.8 A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6: • on the lower left of the marking indicates Pin 1.

\* Weekly code: (three digits)



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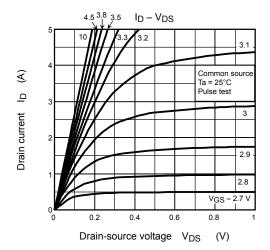


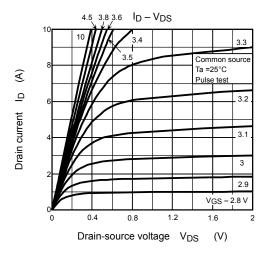
## **Electrical Characteristics (Ta = 25°C)**

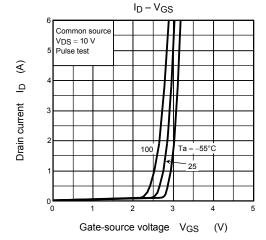
Chara	Characteristic		Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	— ±100		nA
Drain cutoff curr	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	10	μΑ
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	60	_	_	V
Dialii-Source bit	eakdown voltage	V (BR) DSX	$I_D = 10$ mA, $V_{GS} = -20$ V	45	_	_	
Gate threshold v	/oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_D = 0.1 \text{ mA}$	1.3	_	2.3	V
Drain-source Of	l recistance	R <sub>DS</sub> (ON)	$V_{GS} = 4.5 \text{ V}, I_D = 1.9 \text{ A}$	_	43	64	mΩ
Diain-source Or	v-resistance	R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}$ , $I_D = 1.9 \text{ A}$	_ 38 57		11122	
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V , I <sub>D</sub> = 1.9 A	6	12	_	S
Input capacitano	ce	C <sub>iss</sub>		_	640	900	pF
Reverse transfe	r capacitance	C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	25	40	
Output capacitance		C <sub>oss</sub>		_	90	_	
Gate resistance	Gate resistance		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 5 MHz	_	3.2	4.6	Ω
Output capacitan Gate resistance Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> 10 V	_	1.8	_	
	Turn-on time	t <sub>on</sub>		_	6.7	_	
	Fall time	t <sub>f</sub>		_	1.8	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_w = 10~\mu s$	_	18	_	
Total gate charge (gate-source plus gate-drain) (Note 7)			$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.8 \text{ A}$	_	11	_	
		Qg	$V_{DD} \approx 48 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 3.8 \text{ A}$	_	5.7	_	
Gate-source charge 1		Q <sub>gs1</sub>		_	2.1	_	nC
Gate-drain ("Miller") charge		Q <sub>gd</sub>	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.8 \text{ A}$	_	1.8	_	
Gate switch charge		Q <sub>SW</sub>		_	2.6	_	

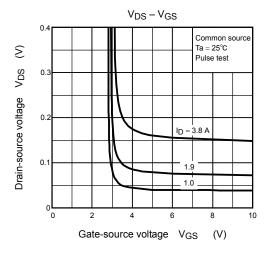
### Source-Drain Ratings and Characteristics (Ta = 25°C)

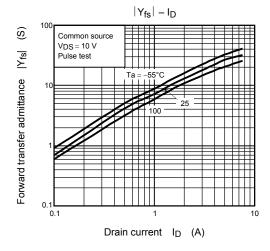
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	15.2	Α
Forward voltage (diode)		V <sub>DSF</sub>	I <sub>DR</sub> = 3.8 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

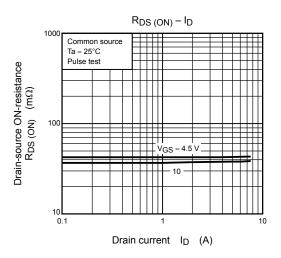




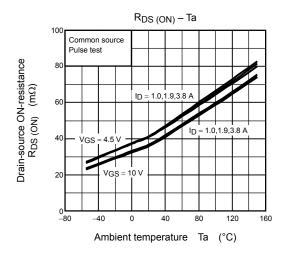


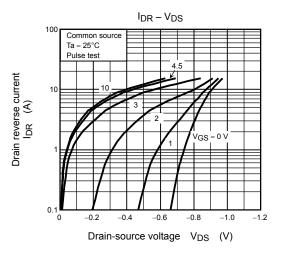


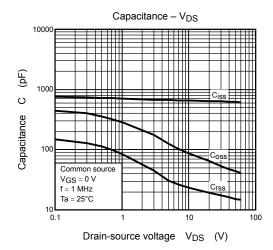


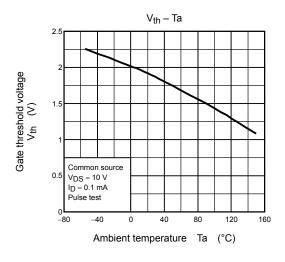


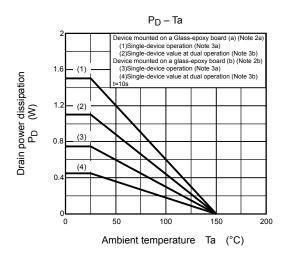
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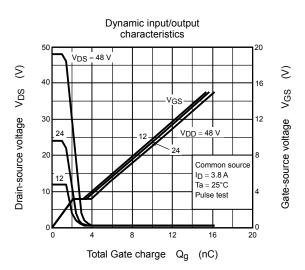




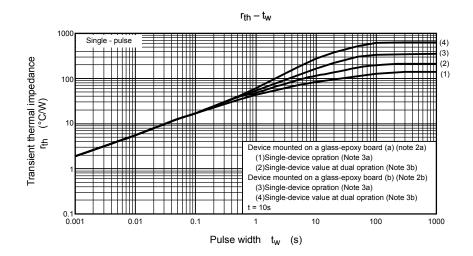


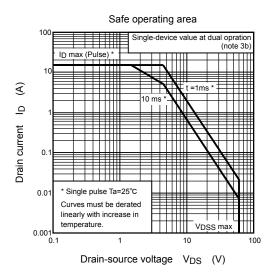






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